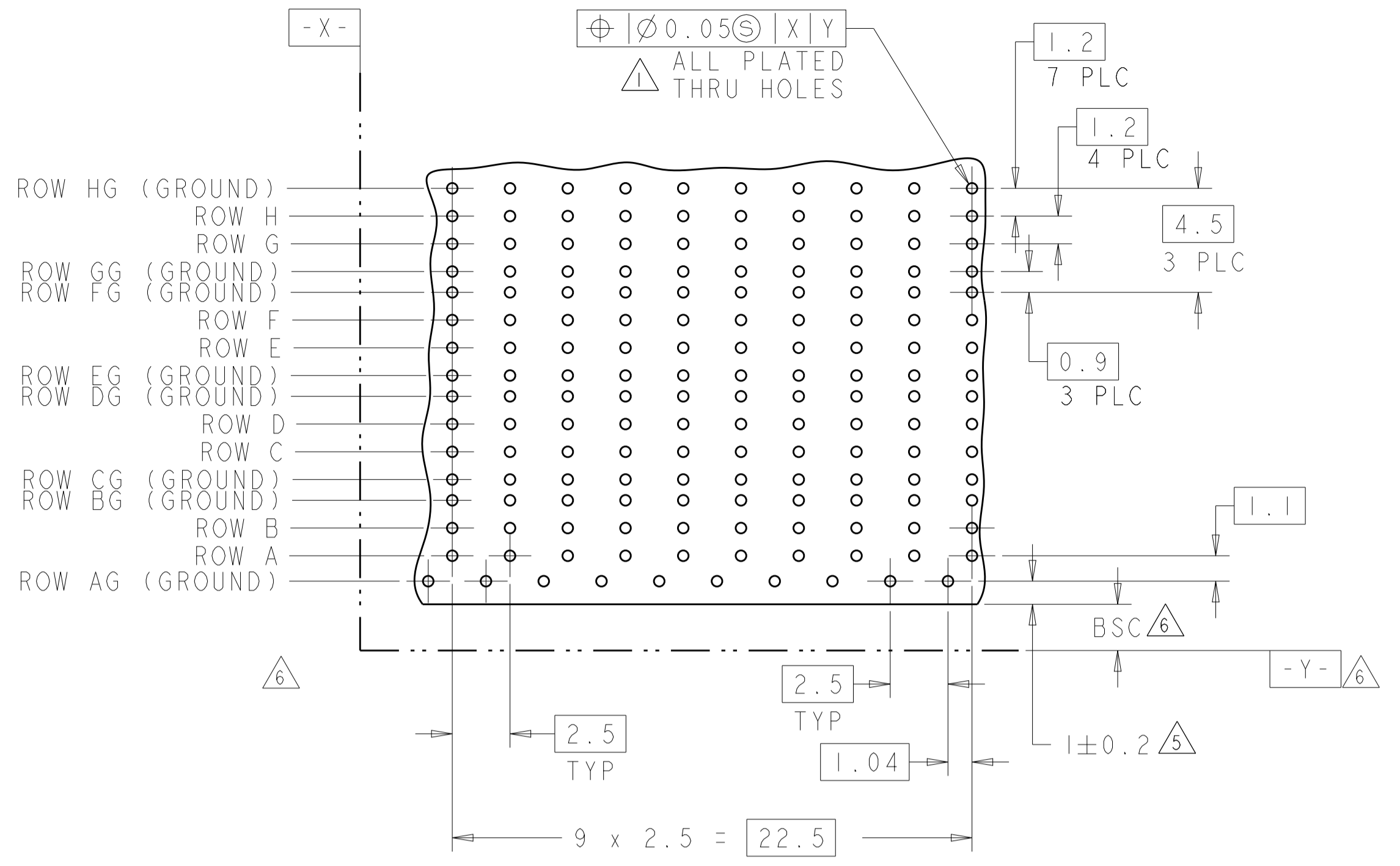
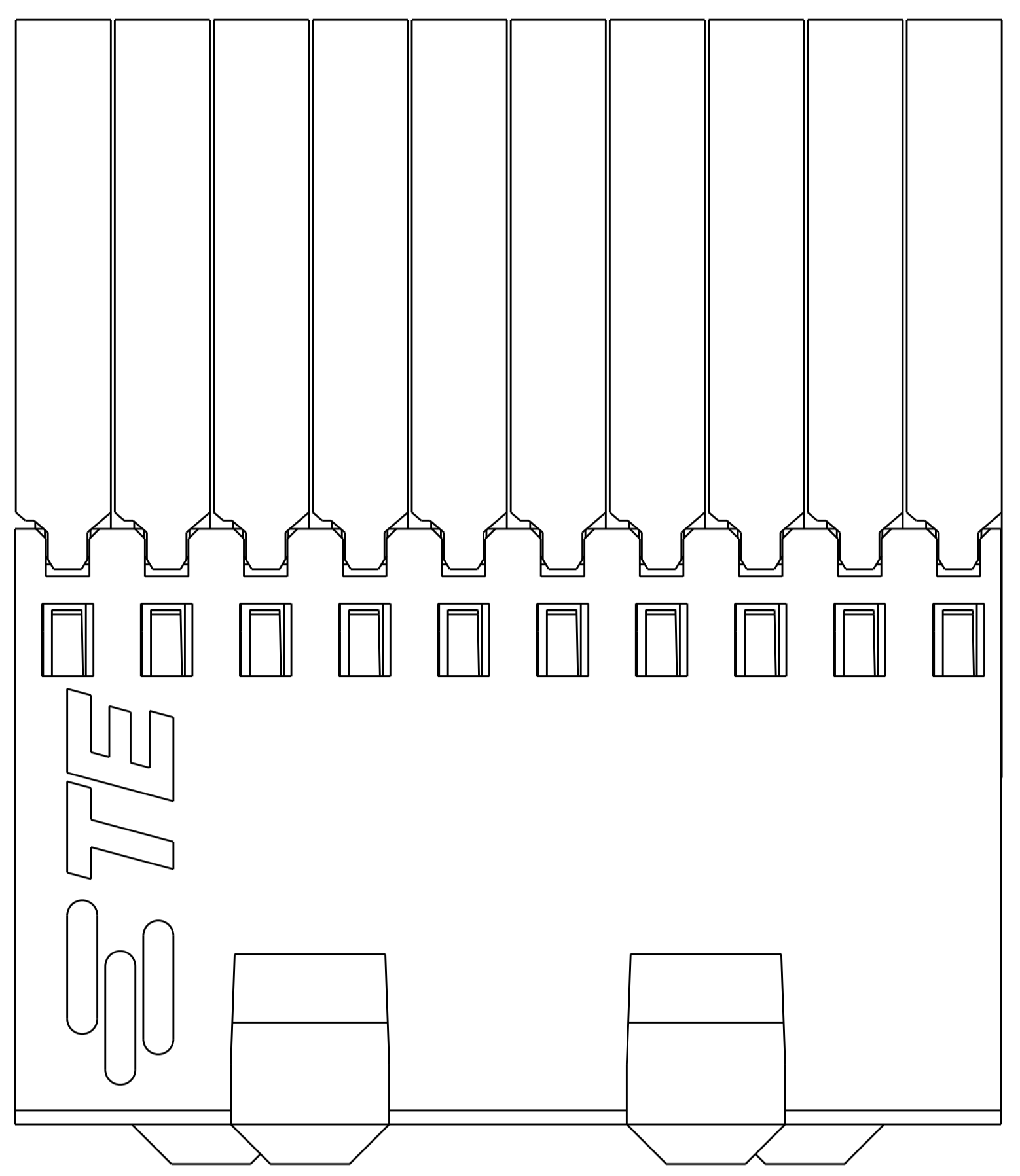
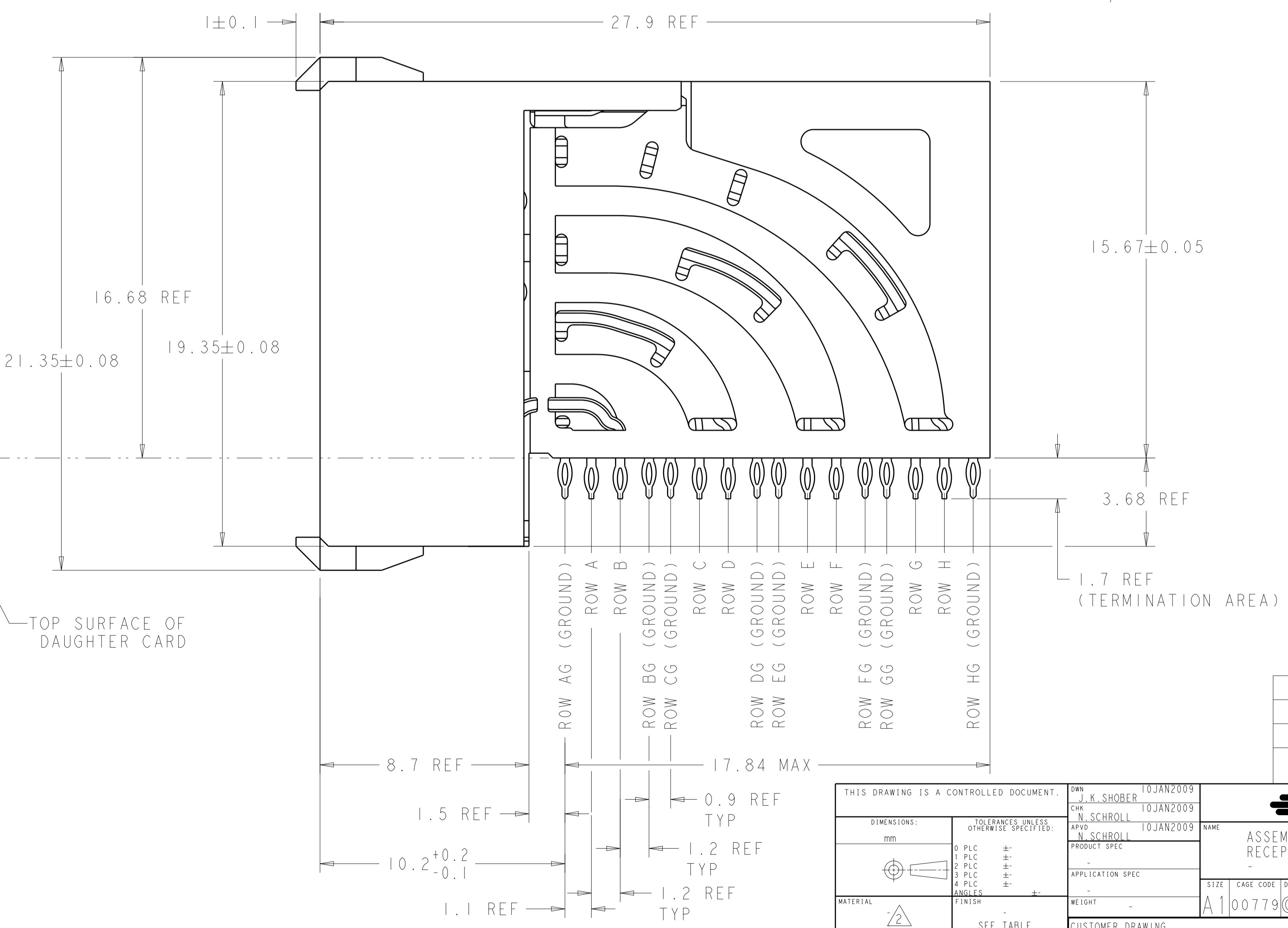
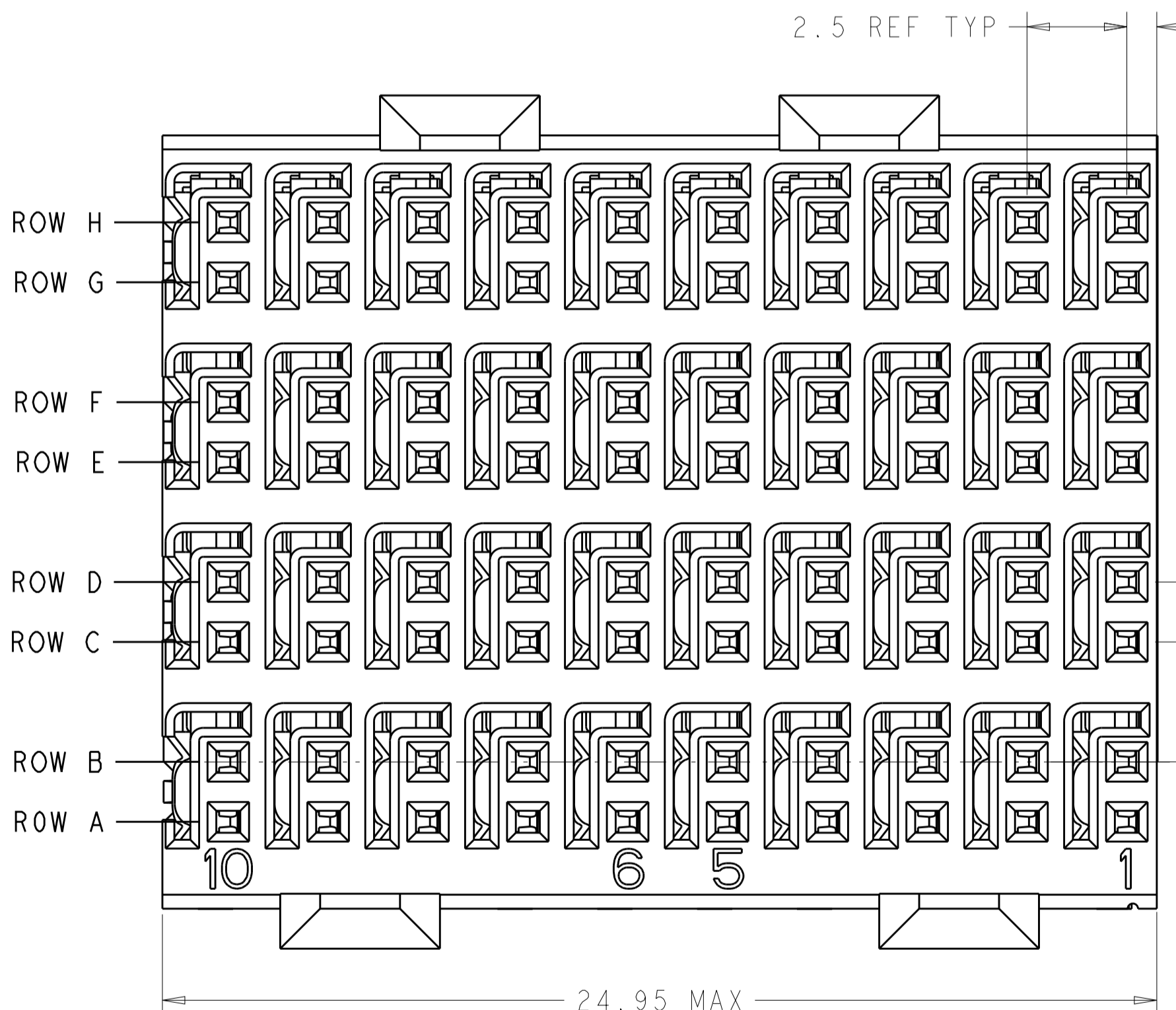


REVISIONS				
P.	LTN.	DESCRIPTION	DATE	APPROVED
C1		REVISED PER ECO-15-012381	27AUG2015	AP RP
D		REVISED PER ECO-16-008845	22SEP2016	AP RP



RECOMMENDED PC BOARD LAYOUT,
 DAUGHTER BOARD,
 COMPONENT SIDE SHOWN
 SCALE 5:1

- 1. REFERENCE APPLICATION SPEC 114-13059 FOR RECOMMENDED PLATED THRU HOLE DIAMETER AND PLATING THICKNESSES.
- 2. MATERIAL:
 SHIELD - PHOSPHOR BRONZE
 CONTACT - COPPER-NICKEL-SILICON
 HOUSING, CHICKLET AND CHICKLET COVER - GLASS FILLED POLYESTER, UL 94V-0 RATED.
- 3. FINISH: CONTACT AND SHIELD MATING AREA:
 MEETS THE PERFORMANCE REQUIREMENTS OF TYCO ELECTRONICS PRODUCT SPECIFICATION, 108-2055-1; BASED ON TELCORDIA GR-1217-CORE, APPLICATIONS IN UNCONTROLLED ENVIRONMENTS.
 COMPLIANT PIN AREA:
 0.5µm MIN BRIGHT TIN/LEAD OVER BASE PLATING.
- 4. CONNECTOR MARKED WITH PART NUMBER AND DATE CODE IN APPROXIMATE AREA SHOWN.
- 5. DIMENSION APPLIES TO CENTERLINE OF THRU HOLE.
- 6. DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- 7. CONTACT AREA LUBRICATED WITH BELLCORE APPROVED LUBRICANT. TECHNICAL REFERENCE: GR-1217-CORE, ISSUE 1, NOVEMBER 1995.
- 8. FINISH: CONTACT AND SHIELD MATING AREA:
 MEETS THE PERFORMANCE REQUIREMENTS OF TYCO ELECTRONICS PRODUCT SPECIFICATION, 108-2055-1; BASED ON TELCORDIA GR-1217-CORE, APPLICATIONS IN UNCONTROLLED ENVIRONMENTS.
 COMPLIANT PIN AREA:
 0.5µm MIN MATTE TIN OVER BASE PLATING.
- 9. FINISH: CONTACT AND SHIELD MATING AREA FINISH: 0.76 MIN GOLD OVER 1.27 MIN NICKEL COMPLIANT PIN AREA: 0.5µm MIN MATTE TIN OVER BASE PLATING.



FINISH	PART NUMBER
9	2065657-3
3	2065657-2
8	2065657-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

OWN: J. K. SHOBER 10JAN2009
 CHK: N. SCHROLL 10JAN2009
 APVD: N. SCHROLL 10JAN2009

TE Connectivity

ASSEMBLY, Z-Pack Hm-Zd Plus, RECEPTACLE, 4 PAIR

SIZE: A1 00779 C=2065657
 SCALE: 8:1 SHEET 1 OF 1 REV D

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)